

SOLDER PASTE

BGA LEAD-FREE SOLDER PASTE



Sn42/Bi58

Melting point 138°C



Product Usage



TIN PASTE

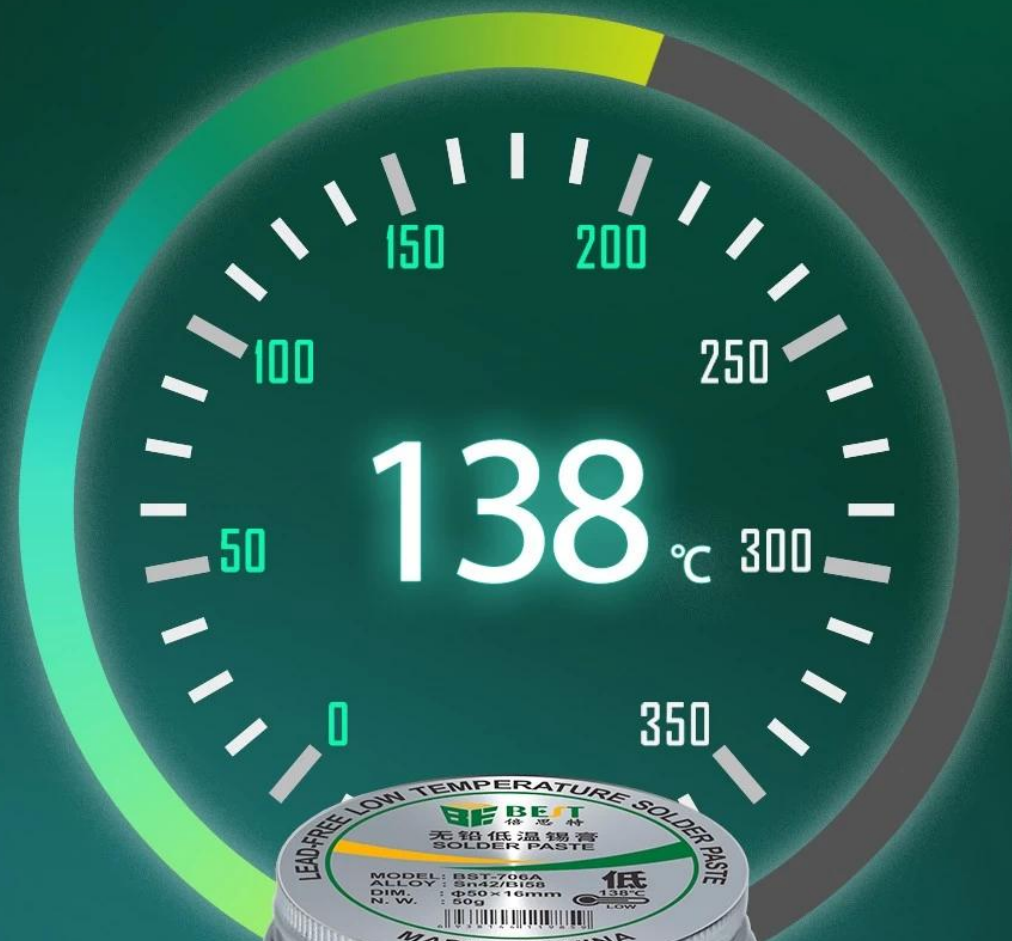
Model	BST-706
Name	Low temperature solder paste
Composition	Sn42/Bi58
Melting point	138℃
G.W.	50g
Granule	20~38μm
Size	φ50*16mm

Sn42/Bi58

Lead-free low temperature melting point

138°C

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Product Size



G.W.:50g

